

03-01-2002

Patent and Trademark Office

6715/66468



To the Honorable Commissioner of Patents and Trademarks

1. Name of conveying party(ies):

Hiroaki Okajima
Akira Shinada
Katsuhiko Nunokawa
Makoto Sasaki
Seiichi Tsunoda

Additional name(s) of conveying party(ies) attached? ☐ Yes ☒ No

Name and address of receiving party(ies):

Name: Sony Corporation

Internal Address: _____

Street Address: 7-35 Kitashinagawa 6-chome
Shinagawa-ku, Tokyo, Japan

City _____ State _____ ZIP _____

Additional name(s) & address(es) attached? ☒ Yes ☐ No

3. Nature of Conveyance:

☒ Assignment

☐ Merger

☐ Security Agreement

☐ Change of Name

☐ Other _____

Execution Date: December 5, 2001,

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is _____

A. Patent Application No.(s)

10/021,866

B. Patent No.(s)

Additional numbers attached? ☐ Yes ☒ No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Jay H. Maioli

Internal Address: Cooper & Dunham LLP

Street Address: 1185 Avenue of the Americas

City: New York State: New York ZIP: 10036

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41): \$ 40.00

☒ Enclosed

☐ Authorized to be charged to deposit account

8. Deposit account number:

03-3125
(Attach duplicate copy of this page if paying by deposit account)

DO NOT USE THIS SPACE

9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Jay H. Maioli, Reg. No. 27,213

Name of Person Signing

Jay H. Maioli
Signature

January 23, 2002

Date

Total Number of pages comprising cover sheet: 1

OMB No. 0651-0011 (exp. 4/94)

Do not detach this portion

Mail documents to be recorded with required cover sheet information to:

02/26/2002 SHINASS1 00000096 10021866

02 FEB 581

40.00 DP

Commissioner of Patents and Trademarks
Box Assignments
Washington, D.C. 20231

Public burden reporting for this sample cover sheet is estimated to average about 30 minutes per document to be recorded, including time for reviewing the document and gathering the data needed, and completing and reviewing the sample cover sheet. Send comments regarding this burden estimate to the U.S. Patent and Trademark Office, Office of Information Systems, PK2-1000C, Washington, D.C. 20231, and to the office of Management and Budget, Paperwork Reduction Project. (0651-0011). Washington, D.C. 20503

PATENT
REEL: 012614 FRAME: 0011

Additional Names and Addresses of Receiving Parties:

**Toyota Jidosha Kabushiki Kaisha
Japanese Corporation
1, Toyota-cho, Toyota-shi, Aichiken,
471-8571, Japan**

ASSIGNMENT

WHEREAS, I, as a below named inventor, residing at the address stated next to my name, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in

VEHICLE POSITIONING APPARATUS, DEVICE, AND METHOD

(title)

for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, Sony Corporation, a Japanese corporation with offices at 7-35, Kitashinagawa 6-chome, Shinagawa-ku, Tokyo, Japan and Toyota Jidosha Kabushiki Kaisha, a Japanese corporation with offices at 1, Toyota-cho, Toyota-shi, Aichi-ken, 471-8571 Japan (hereinafter reference as ASSIGNEES) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEES, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEES, as the assignee of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEES or its designee, as ASSIGNEES or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereof;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEES will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereof;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my attorney(s) of record in this application to insert the serial number and filing date of this application in the spaces that follow:

International Application Number _____
International Filing Date _____
U.S. Serial Number _____
U.S. Filing Date _____

This assignment executed on the dates indicated below.

Hiroaki OKAJIMA December 5, 2001
Name of first or sole inventor Date

Chiba, Japan
Residence of first or sole inventor

Hiroaki Okajima
Signature of first or sole inventor Execution date of U.S. Patent Application

Akira SHINADA
Name of second inventor Date 12.5.2001

Tokyo, Japan
Residence of second inventor

Akira Shinada
Signature of second inventor Execution date of U.S. Patent Application

Katsuhiko NUNOKAWA December 5, 2001
Name of third inventor Date

Kanagawa, Japan
Residence of third inventor

Katsuhiko Nunokawa
Signature of third inventor Execution date of U.S. Patent Application

Docket No. _____

S01P1931US00JTSN20010249US00Makoto SASAKI

Name of fourth inventor

December 5, 2001

Date

Chiba, Japan

Residence of fourth inventor

December 5, 2001Makoto Sasaki Makoto Sasaki Makoto Sasaki.

Signature of fourth inventor

Execution date of U.S. Patent Application

Seiichi TSUNODA

Name of fifth inventor

Date

Nissin-shi, Aichi-ken, Japan

Residence of fifth inventor

Signature of fifth inventor

Execution date of U.S. Patent Application

S01P1931US00J

Docket No. S01P1931US00J
TSN20010249US00

Makoto SASAKI
Name of fourth inventor Date

Chiba, Japan
Residence of fourth inventor

Signature of fourth inventor Execution date of U.S. Patent Application

Seiichi TSUNODA
Name of fifth inventor Date

Dec., 5, 2001

Nissin-shi, Aichi-ken, Japan
Residence of fifth inventor

Seiichi Tsunoda
Signature of fifth inventor Execution date of U.S. Patent Application